

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	AMG/16/9756	
1.3 Title of PCN	SO8 and SO8 exposed pad packaged products lead frame change in ST's subcontractor Amkor	
1.4 Product Category	See product list	
1.5 Issue date	2016-07-05	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	SETTLES JEFF
2.1.2 Phone	+44 1628896222
2.1.3 Email	jeff.settles@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Francesca Marta SANDRINI,Emanuele VAVASSORI,Marcello SAN BIAGIO
2.1.2 Marketing Manager	Vincenzo MONTEMEZZO,Carolina SELVA,Massimiliano MERISIO
2.1.3 Quality Manager	Jean-Marc BUGNARD,Alessandro PLATINI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), lead frame, resin, wire, ...)	AMKOR Philippines (ST's subcontractor)

4. Description of change

	Old	New
4.1 Description	Products in SO8 Exposed Pad and SO8 packages are assembled in Amkor using old Lead Frame Matrix (OMLF) and High Density Lead Frame (HDLF).	SO8 Exposed pad products will be moved to Ultra Density Lead Frame (UDLF). SO8 products will be moved to Xtreme Density Lead Frame (XDLF).
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact on form, fit, function, reliability, or processability	

5. Reason / motivation for change

5.1 Motivation	The purpose of the change from ODLF/HDLF to UDLF/XDLF production format is to enhance the manufacturing process for higher volume production with greater efficiency and productivity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Finish good codes
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7. Timing / schedule

7.1 Date of qualification results	2016-04-30
7.2 Intended start of delivery	2016-09-22
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	9756_Qualif report.zip		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2016-07-05

9. Attachments (additional documentations)		
9756PpPrdtLst.pdf 2_PCN9756_SO8_SO8EXPAD Strip_Lead Frame change to XD_UD in Amkor.pdf 9756_Qualif report.zip		
10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	L5973ADTR	
	L5973D013TR	

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SO8 PACKAGE: Strip Lead Frame change in ST Subcon Amkor ATP

- **SO8: from ODLF to XDLF**
- **SO8Expad: from HDLF to UDLF**

WHAT is the change?

Progressing on activities related to process modernization and quality, STMicroelectronics is pleased to announce the introduction of the Ultra Density Lead Frame (UDLF) and the eXtreme Density Lead frame (XDLF). At the same time there will be the phasing out of the Old Lead Frame Matrix (OMLF) and the High Density Lead Frame (HDLF). This will occur in one of our main assembling Subcontractors (Amkor ATP, Philippines).

The products housed in SO8 package will be moved to the eXtreme Density Lead Frame.

The products housed in SO8 Exposed Pad will be moved to the Ultra Density Lead Frame.

In the annexed list the impacted products for both packages.

Dedicated engineering trials and Test vehicles have been defined to validate the change.

WHY:

The purpose of the change from ODLF/HDLF to UDLF/XDLF production format is to enhance the manufacturing process to improve the production volumes with the greatest efficiency and productivity.

WHEN will this change occur?

The change will start gradually. As mentioned earlier this transfer is completing what already initiated. Most of the Qualification Reports are based on automotive line codes.

Package	Test vehicles by Commercial Products/Line codes	Test Vehicles Samples availability	Qualification Report availability (upon request)	Estimated First Shipment start date
SO8 – EXP PAD	L5875DTR/UK17	Upon request	Preliminary available. Final WK44	End of Q4-216
	L7985ATR/UA50	Upon request	Available	End of Q2-2016
	L5973D/UD73	Upon request	Available	End of Q2-2016
	L5975ADTR/UK18	Upon request	Preliminary available WK44	End of Q4-216
	L5973ADTR/UT20	Upon request	Available	End of Q2-2016
	ST1S10PHR/UM85	Upon request	Available	End of Q3-2016
SO8	U093	Upon request	Available	End of Q2-216

HOW will the change be qualified?

- The present notification is concerning consumer and industrial products and the change is only relative to Lead Frame strip density.
 - For SO8-Exp Pad packaged products, the qualification is based on the similar automotive product lines, following AEC-Q100 specification. For these product lines the PCN has been already issued.
 - For SO8 packaged products, the qualification is based on a representative Test vehicle by using internal ST rule for changes.

IMPACTS OF THE CHANGE:

Form: No change
Fit: No change
Function: No change



Public Products List

PCN Title : SO8 and SO8 exposed pad packaged products lead frame change in ST's subcontractor Amkor

PCN Reference : AMG/16/9756

PCN Created on : 18-Apr-2016

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

L7985A	ST1S40IPHR	L5973ADTR
ST1S10PHR	L7980A	L7986A
L7985ATR	L7986ATR	L7980ATR
SRK2000D	L5986A	L5973D013TR
LED2001PHR	L7981ATR	SRK2000DTR
L5987ATR	L5973D	STCS1PHR
L7981A	L7986TATR	ST1S14PHR
L7986TA	L5986ATR	L5973AD
L5970D013TR	L5970D	STCS1APHR
SRK2000A	LED5000PHR	L5987A
SRK2000ATR	L6932H1.2	ST1S41PHR
L6932H1.2TR		



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